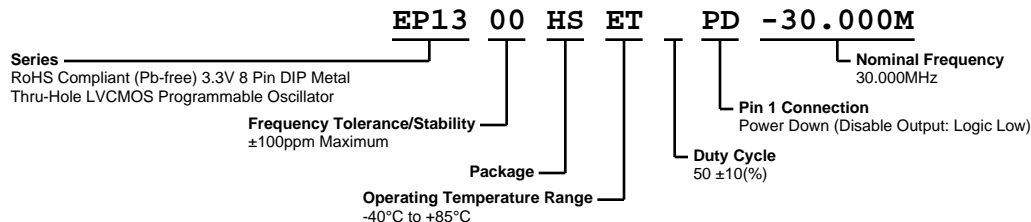


EP1300HSETPD-30.000M



ELECTRICAL SPECIFICATIONS

Nominal Frequency	30.000MHz
Frequency Tolerance/Stability	$\pm 100\text{ppm}$ Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C , Shock, and Vibration)
Aging at 25°C	$\pm 5\text{ppm/year}$ Maximum
Operating Temperature Range	-40°C to $+85^{\circ}\text{C}$
Supply Voltage	3.3Vdc $\pm 0.3\text{Vdc}$
Input Current	28mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	Vdd-0.4Vdc Minimum (IOH = -8mA)
Output Voltage Logic Low (Vol)	0.4Vdc Maximum (IOL = +8mA)
Rise/Fall Time	4nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	$50 \pm 10\%$ (Measured at 50% of waveform)
Load Drive Capability	30pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Power Down (Disable Output: Logic Low)
Pin 1 Input Voltage (Vih and Vil)	70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output, No Connect to enable output.
Standby Current	20 μA Maximum (Pin 1 = Ground)
Disable Current	16mA Maximum (Pin 1 = Ground)
Peak to Peak Jitter (tPK)	100pSec Maximum, 60pSec Typical
RMS Period Jitter (tRMS)	13pSec Maximum, 10pSec Typical
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to $+125^{\circ}\text{C}$

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

EP1300HSETPD-30.000M

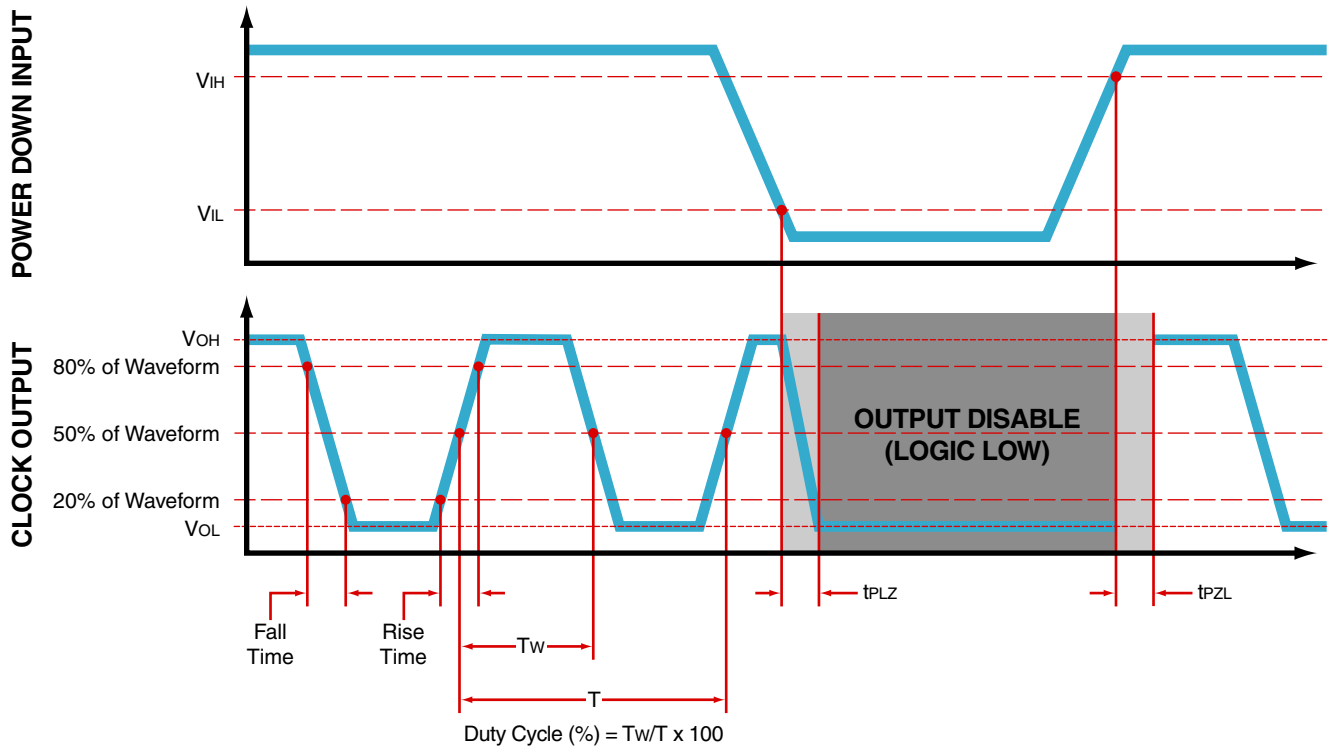
MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Power Down (Logic Low)
4	Case/Ground
5	Output
8	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	EP13PD EP13=Product Series
3	30.000M
4	XXYYZ XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year

OUTPUT WAVEFORM & TIMING DIAGRAM



EP1300HSETPD-30.000M

Test Circuit for CMOS Output



Note 1: An external $0.1\mu\text{F}$ low frequency tantalum bypass capacitor in parallel with a $0.01\mu\text{F}$ high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

Note 2: A low capacitance ($<12\text{pF}$), 10X attenuation factor, high impedance ($>10\text{Mohms}$), and high bandwidth ($>300\text{MHz}$) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

T_s MAX to T_L (Ramp-up Rate)	3°C/second Maximum
Preheat	
- Temperature Minimum (T_s MIN)	150°C
- Temperature Typical (T_s TYP)	175°C
- Temperature Maximum (T_s MAX)	200°C
- Time (t_s MIN)	60 - 180 Seconds
Ramp-up Rate (T_L to T_p)	3°C/second Maximum
Time Maintained Above:	
- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds
Peak Temperature (T_p)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T_p Target)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 seconds
Ramp-down Rate	6°C/second Maximum
Time 25°C to Peak Temperature (t)	8 minutes Maximum
Moisture Sensitivity Level	Level 1

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 185°C

T_s MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_s MIN) N/A
- Temperature Typical (T_s TYP) 150°C
- Temperature Maximum (T_s MAX) N/A
- Time (t_s MIN) 60 - 120 Seconds

Ramp-up Rate (T_L to T_p) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
- Time (t_L) 200 Seconds Maximum

Peak Temperature (T_p) 185°C Maximum

Target Peak Temperature (T_p Target) 185°C Maximum 2 Times

Time within 5°C of actual peak (t_p) 10 seconds Maximum 2 Times

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

T_s MAX to T_L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T_s MIN)	N/A
- Temperature Typical (T_s TYP)	150°C
- Temperature Maximum (T_s MAX)	N/A
- Time (t_s MIN)	30 - 60 Seconds
Ramp-up Rate (T_L to T_p)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T_L)	150°C
- Time (t_L)	200 Seconds Maximum
Peak Temperature (T_p)	245°C Maximum
Target Peak Temperature (T_p Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (t_p)	5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.